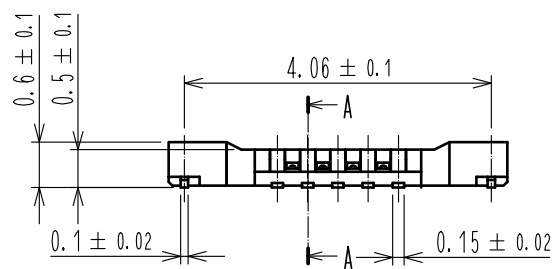
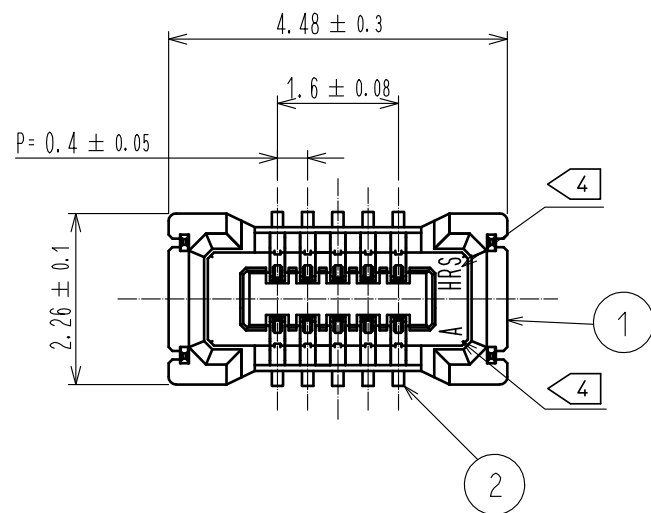
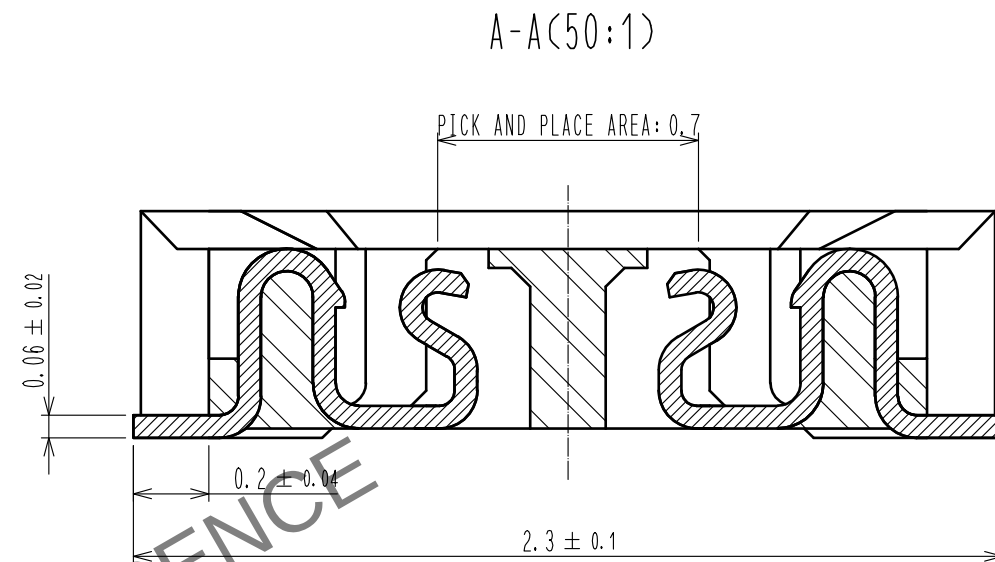


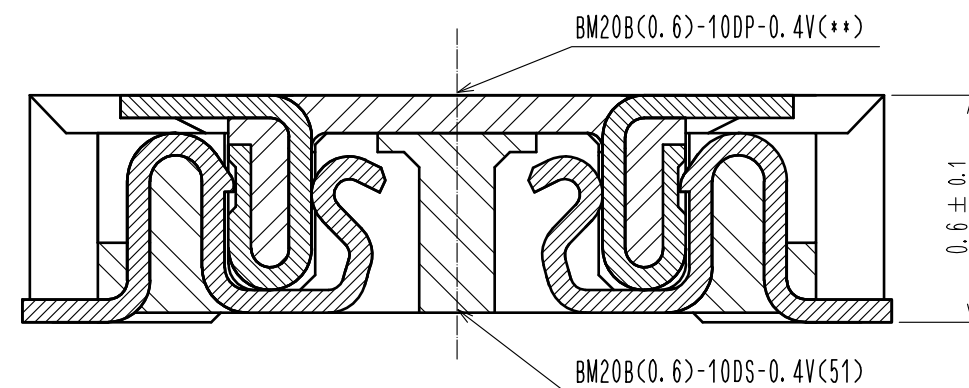
Apr.1.2024 Copyright 2024 HIROSE ELECTRIC CO., LTD. All Rights Reserved.
In case of consideration for using Automotive equipment / device which demand high reliability, kindly contact our sales window correspondents.



- NOTE 1. ALL LEAD CO-PLANARITY SHALL BE 0.08mm MAX
2. CONTACT PLATING SPECIFICATIONS
CONTACT AREA : GOLD 0.05μm MIN
SMT LEAD : GOLD 0.05μm MIN
UNDERPLATING : NICKEL 1μm MIN
(SURFACE : SEALING)
3. METAL FITTING PLATING SPECIFICATIONS
SMT LEAD : GOLD 0.05μm MIN
UNDERPLATING : NICKEL 1μm MIN
(SURFACE : SEALING)
4. HRS MARK AND CAV NO. ARE INDICATED IN APPROX POSITION SHOWN.



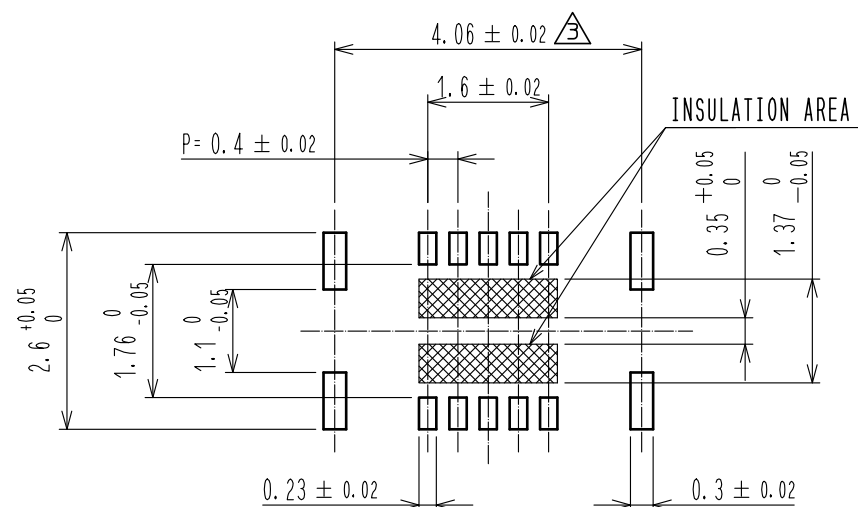
ENGAGEMENT FIGURE (50:1)



4	PS	CLEAR (EMBOSSED CARRIER TAPE)			
3	BRASS	3	7	PS	CLEAR (REINFORCEMENT COLLAR)
2	PHOSPHOR BRONZE	2	6	PS	BLACK (PLASTIC REEL)
1	LCP	UL94 V-0, BLACK	5	POLYESTER	CLEAR (COVER TAPE)
NO.	MATERIAL	FINISH , REMARKS	NO.	MATERIAL	FINISH , REMARKS
UNITS mm		SCALE 10 : 1	COUNT 3	DESCRIPTION OF REVISIONS DIS-H-00003231	DESIGNED RT. SHIMIZU
HIROSE ELECTRIC CO., LTD.		APPROVED : KH. IKEDA	12.11.05	DRAWING NO.	EDC3-347095-51
		CHECKED : WR. FUKUCHI	12.11.05	PART NO.	BM20B(0.6)-10DS-0.4V(51)
		DESIGNED : RT. SHIMIZU	12.11.05	CODE NO.	CL684-9308-8-51
		DRAWN : RT. SHIMIZU	12.11.05		
				CHECKED	TS. MIYAZAKI
				DATE	17.11.02

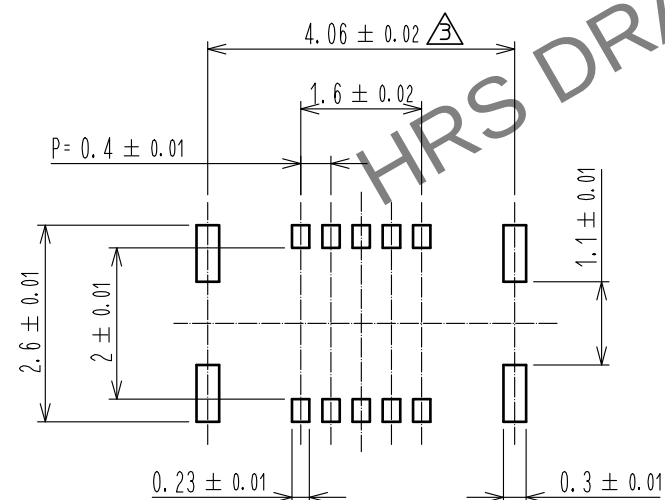
Apr.1.2024 Copyright 2024 HIROSE ELECTRIC CO., LTD. All Rights Reserved.
In case of consideration for using Automotive equipment / device which demand high reliability, kindly contact our sales window correspondents.

◆RECOMMENDED PCB LAYOUT

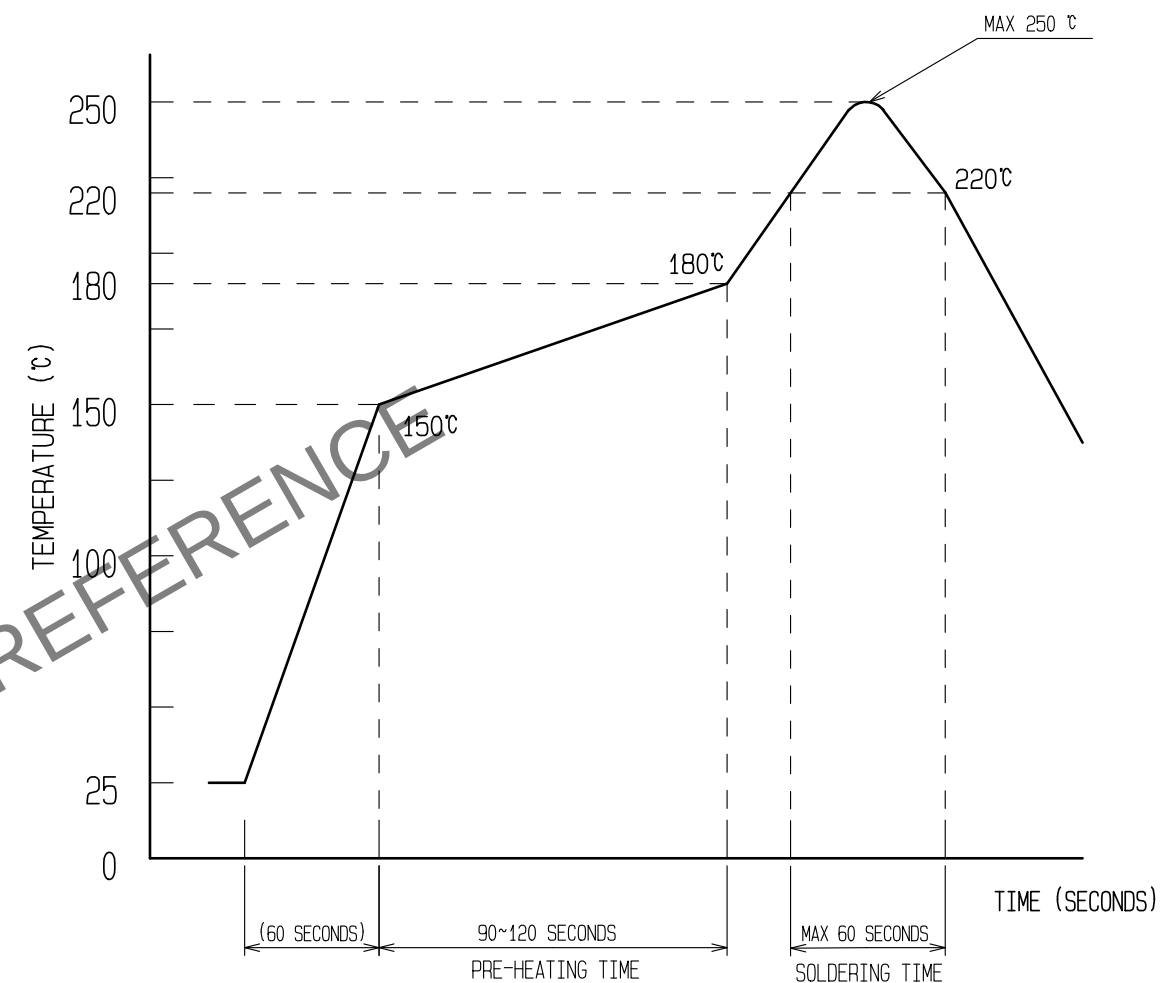


◆RECOMMENDED METAL MASK DIMENSIONS

MATAL MASK THICKNESS : $100 \mu\text{m}$



5 RECOMMENDED REFLOW TEMPERATURE PROFILE USING LEAD-FREE SOLDER PASTE.



REFLOW METHOD : IR REFLOW

NUMBER OF REFLOW CYCLES : 2 CYCLES MAX.

1) REFLOW TIME

DURATION ABOVE 220°C, 60 SEC MAX.
(PEAK TEMPERATURE : 250°C MAX)

2) PRE-HEAT TIME

PRE-HEAT TEMPERATURE(MIN): 150°C
PRE-HEAT TEMPERATURE(MAX): 180°C
PRE-HEAT TIME: 90-120 SEC.

5 THE TEMPERATURE PROFILE IS PER THE CONDITIONS SHOWN ABOVE.
ADDITIONAL FACTORS, SUCH AS SOLDER PASTE TYPE, PCB SIZE AND
OTHER MOUNTED COMPONENTS COULD AFFECT THE PROFILE, THEREFORE,
A THOROUGH EVALUATION OF MOUNTING CONDITION IS REQUIRED
PRIOR TO PRODUCTION. TEMPERATURE IS MEASURED AT CONTACT LEAD.

HRS

DRAWING NO.	EDC3-347095-51
PART NO.	BM20B(0.6)-10DS-0.4V(51)
CODE NO.	CL684-9308-8-51

3/2/3

